SMD LED, Infrared diode

BL-LS3535H0C1IR

■ Features:

■ SMD LEDs , 3.5mmx3.5mm SMD,Infrared diode

- ➢ High Reliability
- ➢ Peak Wavelength at 940, 880, 850nm
- ➢ Water Clear, Blue Transparent available
- ➢ IC compatible /Low current capability.
- ➢ PACKAGE: 1KPCS/REEL.
- ➢ RoHs Compliance





■ Applications:

- ➢ Free air transmission system
- ➢ Smoke detector
- ➢ Infrared Camera
- ➢ Optoelectronic switch
- ➢ Infrared applied system

■ Electrical-optical characteristics: (Ta=25°C) (Test Condition: IF=1000mA)

Part Number	Chip		Lens Type	Δλ	Ir (Vr=5V, uA)	Forward Voltage(VF) Unit:V		Radiant Power (mw/sr)	Viewing Angle 2θ1/2(deg)
	Material	λP (nm)				Typ	Max	Typ	
BL-LS3535H0C1IRAC	GaAs	940	Water Clear	45	50	1.40	2.0	720	120
BL-LS3535H0C1IRAB	GaAs	940	Blue Trans.	45	50	1.40	2.0	720	
BL-LS3535H0C1IRBC	GaAlAs	880	Water Clear	45	50	1.40	2.0	720	
BL-LS3535H0C1IRBB	GaAlAs	880	Blue Trans.	45	50	1.40	2.0	720	
BL-LS3535H0C1IRCC	GaAlAs	850	Water Clear	45	50	1.40	2.0	600	
BL-LS3535H0C1IRCB	GaAlAs	850	Blue Trans.	45	50	1.40	2.0	600	
BL-LS3535H0C1IRCY	GaAlAs	850	Yellow Trans.	45	50	1.40	2.0	600	

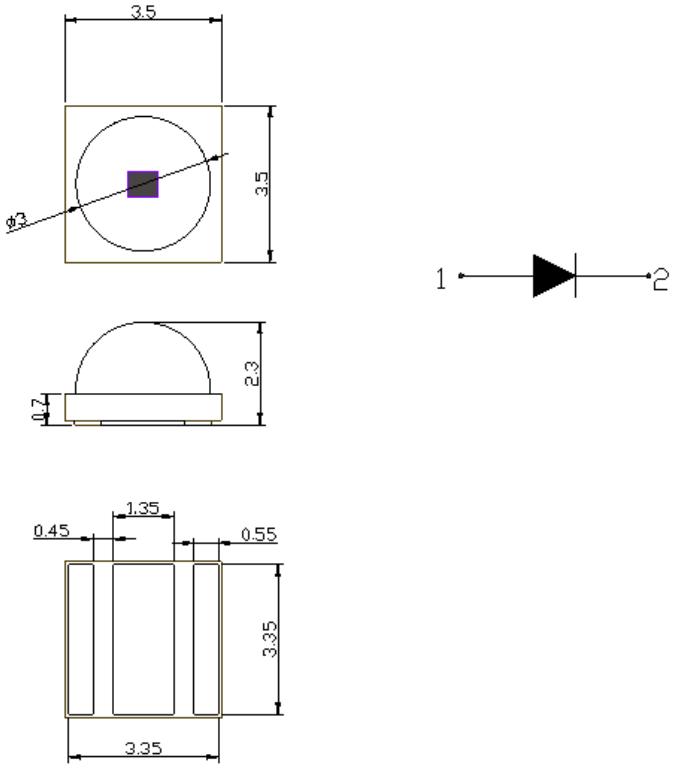
■ Absolute maximum ratings (Ta=25°C)

Parameter	Rating	Unit
Forward Current I_F	1000	mA
Power Dissipation P_d	3	W
Reverse Voltage V_R	5	V
Peak Forward Current I_{PF} (Duty 1/10 @1KHZ)	1400	mA
Operation Temperature T_{OPR}	-40 to +100	°C
Storage Temperature T_{STG}	-40 to +100	°C
Lead Soldering Temperature T_{SOL}	Max.260±5°C for 3 sec Max. (1.6mm from the base of the epoxy bulb)	°C

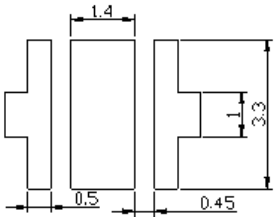
■ Package configuration & Internal circuit diagram

BL-LS3535H0C1 Series

Package Outline Drawing



Recommended Soldering Pad Dimensions

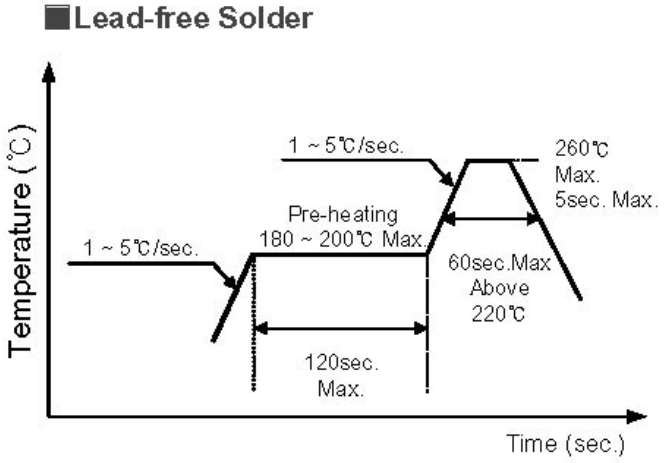


Notes:
1. All dimensions are in millimeters (inches)
2. Tolerance is ±0.25(0.01")unless otherwise noted.
3. Specifications are subject to change without notice.

■ Tape Specifications

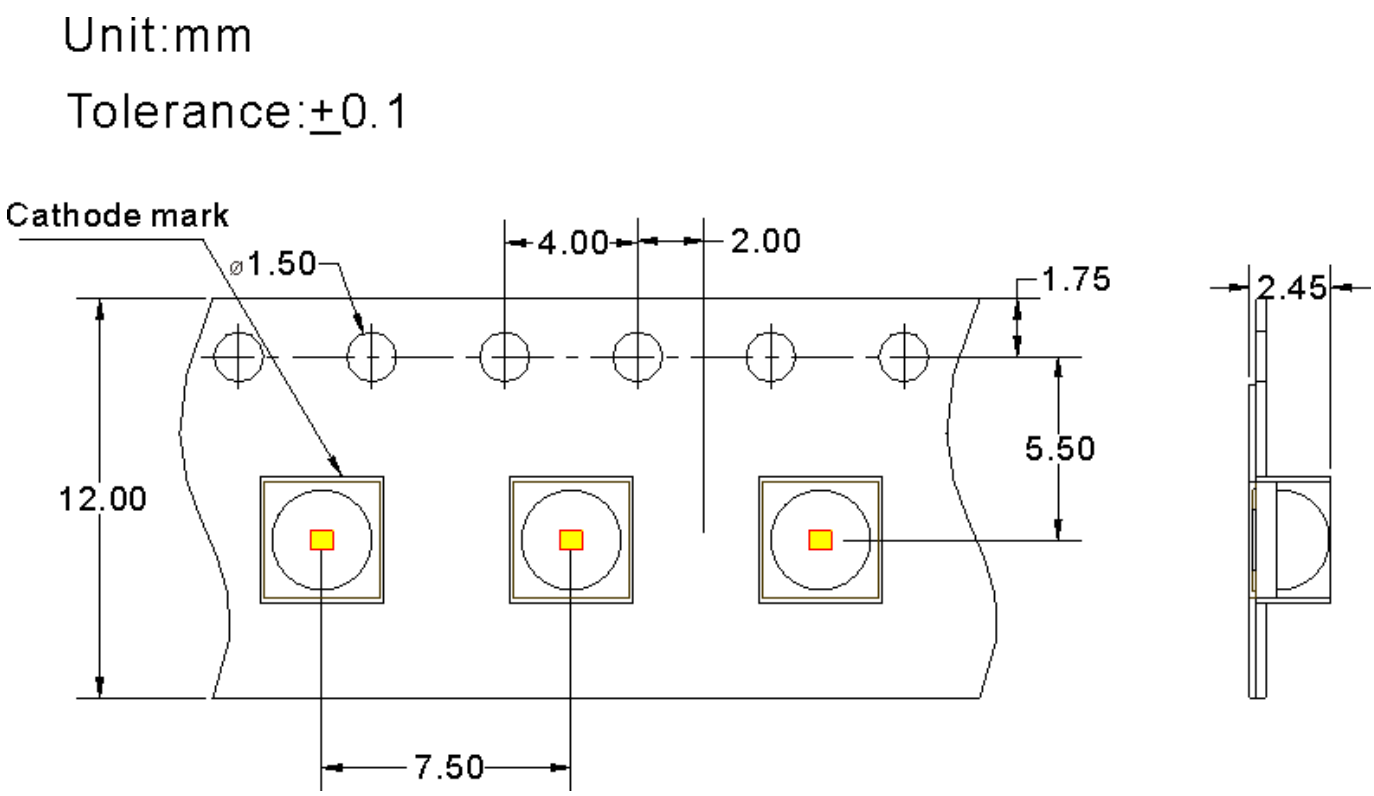
Smt Reflow Solding Instructions

Number of reflow process shall be less than 2 times
and cooling process to normai temperature is required
between first and second soldering process



■ Tape Specifications

(Units:mm)



■ Packing and weighting

